**Wire bonder**

"TPT HB05” manual wire bonder allows the fabrication of the electrical connections between elements as small as 50x50 µm. There are 3 bonding configurations possible:

1. Aluminium wire 25µm thick - wedge - wedge bonding.

2. Golden wire 25µm thick - wedge - wedge and ball - wedge bonding.

3. Golden ribbon with the dimensions of 13 µm (0.5 mil) x 76 µm (3 mil).

The digital target kit, which is also included, makes the whole process easier and is very useful from an educational point of view since the young adepts of the art of wire bonding can now see the whole process themselves. The usage of golden and aluminum wires allows us to bond samples containing graphene as well as silicon and other 3D crystals. The ribbon is used for elements working with high-frequency signals. The relatively low reactance of the ribbon, when compared to the common wire, makes the observation of such high-frequency signals possible.



